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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Charles W.C. Lin  
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA  
Serial No.: 09/852,824 Filed: May 10, 2001  
Examiner: Unknown Group Art Unit: 2812  
Atty. Docket No.: P002-2

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ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

**INFORMATION DISCLOSURE STATEMENT**

Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98,  
Applicant hereby provides a copy of the documents identified on the enclosed Form PTO-1449.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, an admission that any of these documents, alone or in any combination, is considered to be material to patentability, an admission that any of these documents is prior art as to the above-identified application, or an admission against interest in any manner.

This Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits. Accordingly, no fee is due. 37 C.F.R. § 1.97(b)(3).



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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on January 28, 2002.

*D. Sigmond*

David M. Sigmond  
Attorney for Applicant

1/28/02  
Date of Signature

Respectfully submitted,

*D. Sigmond*

David M. Sigmond  
Attorney for Applicant  
Reg. No. 34,013  
(303) 554-8371  
(303) 554-8667 (fax)